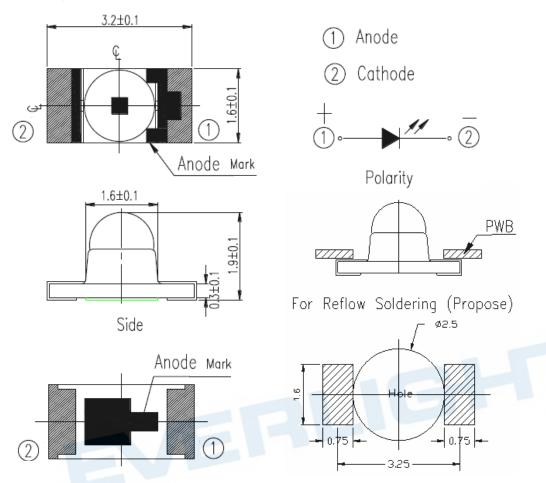
### **Package Dimensions**



Notes: 1.All dimensions are in millimeters

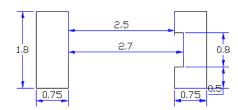
- 2.Tolerances unless dimensions ±0.1mm
- 3. To avoid solder ball problem, below is stencil design suggestion (Reference):

狀態:Approved(正式發行)

Solder paste : Sn/Ag3.0/Cu0.5

Stencil thickness: 0.10mm

Stencil design drawing :



4.Suggested pad dimension is just for reference only
Please modify the pad dimension based on individual need



### Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units	
Continuous Forward Current	I <sub>F</sub>	50	mA	
Peak Forward Current *1	I <sub>FP</sub>	0.5	Α	
Reverse Voltage	$V_R$	5	V	
Operating Temperature	$T_{opr}$	-40 ~ +85	°C	
Storage Temperature	T <sub>stg</sub>	-40~+100	°C	
Soldering Temperature *2	T <sub>sol</sub>	260	°C	
Power Dissipation at(or below) 25°CFree Air Temperature	P <sub>d</sub>	130	mW	

Notes: \*1: $I_{FP}$  Conditions--Pulse Width  $\leq$  100 $\mu$ s and Duty  $\leq$  1%.

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Units
		I <sub>F</sub> =20mA	15	24		
Radiant Intensity	le	$\begin{array}{c} I_F \!\!=\!\! 70 \text{mA} \\ \text{Pulse width } \leq \! 100 \text{us} \text{ , duty} \! \leq \! 1\% \end{array}$		75		mW/sr
Peak Wavelength	λр	I <sub>F</sub> =20mA		850		nm
Spectral Bandwidth	Δλ	I <sub>F</sub> =20mA		30		nm
Forward Voltage V <sub>F</sub>		I <sub>F</sub> =20mA	1.20	1.45	1.70	V
		$\begin{array}{c} I_F \!\!=\! 100 mA \\ \text{Pulse width } \leq \! 100 us \text{ , duty} \! \leq \! 1\% \end{array}$	1.40	1.60	2.00	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V			10	μA
View Angle	201/2	I <sub>F</sub> =20mA		20		deg

<sup>\*2:</sup>Soldering time≦ 5 seconds.

# **Typical Electro-Optical Characteristics Curves**

Fig.1 Forward Current vs.



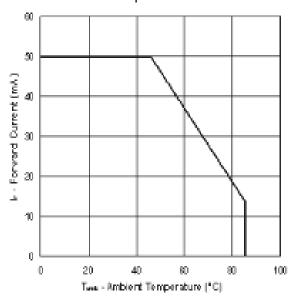


Fig.2 Spectral Distribution

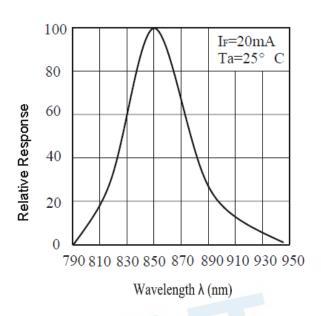


Fig.3 Forward Current vs

Forward Voltage

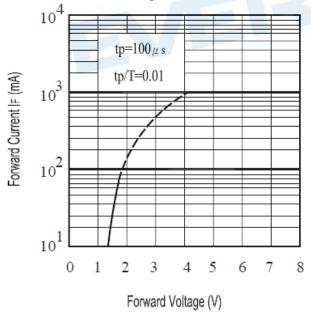
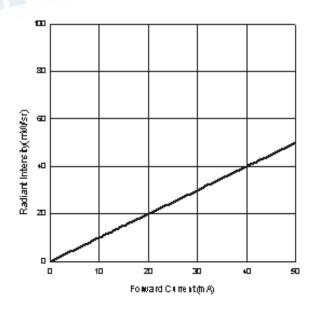


Fig.4 Radiant Intensity vs. **Forward Current** 

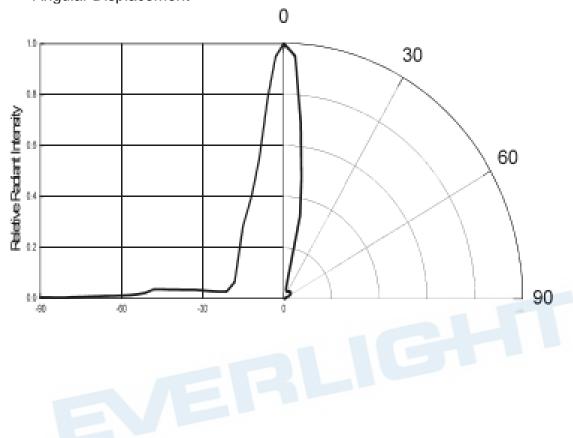




# **Typical Electro-Optical Characteristics Curves**

Fig.5 Relative Radiant Intensity vs.

**Angular Displacement** 





#### **Precautions For Use**

1. Over-current-proof

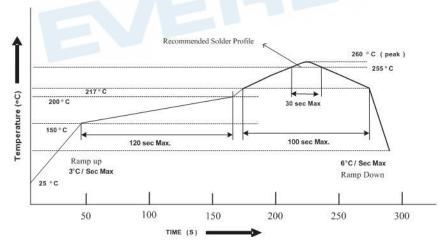
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 10°C ~30°C and 90%RH or less.
- 2.3 The LEDs suggested be used within one year.
- 2.4 After opening the package, the devices must be stored at 10°C~30°C and ≤ 60%RH, and used within 168 hours (floor life). If unused LEDs remain, it should be stored in moisture proof packages.
- 2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag haexceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
- 2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:
  - 96 hours at 60°C ± 5°C and < 5 % RH (reeled/tubed/loose units)

#### 3. Soldering Condition

3.1 Pb-free solder temperature profile



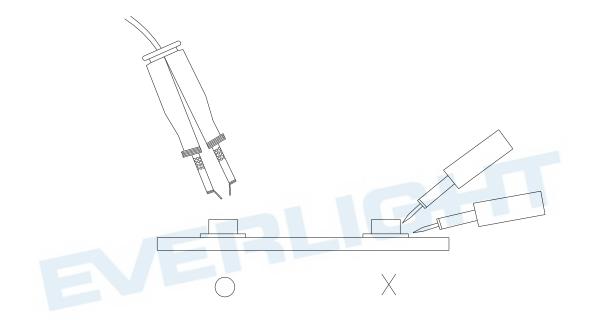
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 4. Soldering Iron

Downloaded from Arrow.com.

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

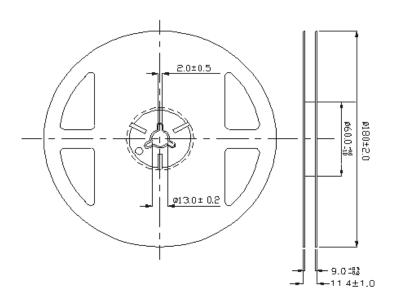
#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



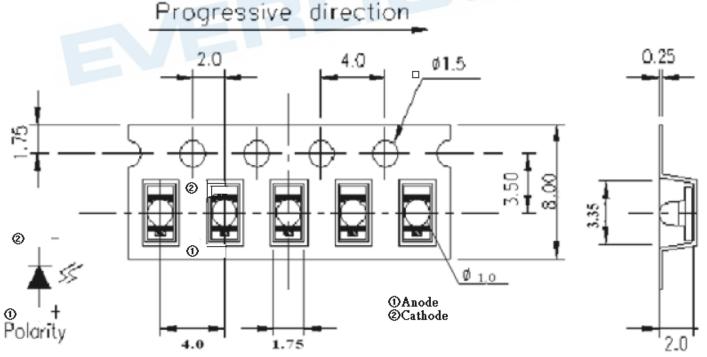


### **Package Dimensions**



Note: The tolerances unless mentioned are ±0.1mm, Unit:mm

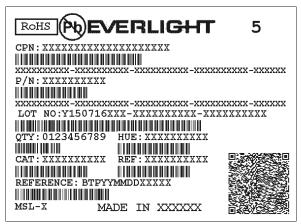
# Carrier Tape Dimensions (Loaded Quantity 1500PCS/reel)



Note: The tolerances unless mentioned are ±0.1mm, Unit:mm



### **Label Form Specification**



CPN: Customer's Production Number

P/N: Production Number QTY: Packing Quantity

CAT: Ranks

**HUE: Peak Wavelength** 

**REF: Reference** 

LOT No: Lot Number MSL-X: MSL Level

Made In: Manufacture place

#### **DISCLAIMER**

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 5. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without obtaining EVERLIGHT's prior consent.
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